

<b>PART INFORMATION</b>	
Mfg Item Number	MPXM2010GS
Mfg Item Name	SNSR M-PAK 05 PORTED
<b>SUPPLIER</b>	
Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2011-11-16
Response Document ID	0885K50010S208A1.15
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
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Representative Title	EPP Customer Response
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URL for Additional Information	www.freescale.com
<b>DECLARATION</b>	
EU RoHS	Yes
Pb Free	Yes
HalogenFree	Yes
Plating Indicator	e4
EU RoHS Exemption(s)	
<b>MANUFACTURING</b>	
Mfg Item Number	MPXM2010GS
Mfg Item Name	SNSR M-PAK 05 PORTED
Version	ALL
Weight	0.527800
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	
Peak Processing Temperature	
Max Time at Peak Temperature	
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	<p>Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.</p>
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemptions in this part	
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

## MATERIAL COMPOSITION

SubPart	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	REACHPPM	REACH%
Non-Conductive Epoxy/Adhesive	0.0041	Solvents, additives, and other materials	Other organic Silicon Compounds	-	0.000011	g	2681	0.2681		20	0.002
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Other siloxanes and silicones	-	0.003429	g	836461	83.6461		6496	0.6496
Non-Conductive Epoxy/Adhesive		Glass	Other silica compounds	-	0.00066	g	160858	16.0858		1250	0.125
Cap/Cover	0.0766	Metals	Aluminum, metal and alloys	7429-90-5	0.000204	g	2669	0.2669		386	0.0386
Cap/Cover		Metals	Chromium, metal and alloys	7440-47-3	0.013113	g	171188	17.1188		24844	2.4844
Cap/Cover		Metals	Copper, metal and alloys	7440-50-8	0.000005	g	63	0.0063		9	0.0009
Cap/Cover		Solvents, additives, and other materials	Sulfur	7704-34-9	0.000015	g	201	0.0201		28	0.0028
Cap/Cover		Solvents, additives, and other materials	Nitrogen peroxide	10102-44-0	0.000231	g	3021	0.3021		437	0.0437
Cap/Cover		Solvents, additives, and other materials	Phosphorus	7723-14-0	0.000174	g	2266	0.2266		329	0.0329
Cap/Cover		Solvents, additives, and other materials	Silicon	7440-21-3	0.000347	g	4531	0.4531		657	0.6557
Cap/Cover		Metals	Iron, metal and alloys	7439-89-6	0.055924	g	730064	73.0064		105957	10.5957
Cap/Cover		Metals	Manganese, metal and alloys	7439-96-5	0.001736	g	22657	2.2657		3289	0.3289
Cap/Cover		Metals	Nickel, metal and alloys	7440-02-0	0.003278	g	42797	4.2797		6210	0.621
Cap/Cover		Metals	Titanium (IV) Oxide	13463-67-7	0.001311	g	17119	1.7119		2483	0.2483
Cap/Cover		Solvents, additives, and other materials	Carbon	7440-44-0	0.000262	g	3424	0.3424		496	0.0496
Port	0.141					g					
Port		Plastics/polymers	Polyphenylene Sulfide (PPS)	26125-40-6	0.08403	g	595960	59.596		159210	15.921
Port		Glass	Proprietary Material-Other glass compounds (without lead, chromium, cadmium or mercury)	-	0.05697	g	404040	40.404		107939	10.7939
Bonding Wire	0.0005					g					
Bonding Wire		Metals	Gold, metal and alloys	7440-57-5	0.0005	g	1000000	100		847	0.0947
Gel Die Encapsulant	0.0165					g					
Gel Die Encapsulant		Solvents, additives, and other materials	Proprietary Material-Other siloxanes and silicones	-	0.014741	g	951021	95.1021		27929	2.7929
Gel Die Encapsulant		Solvents, additives, and other materials	Dimethyl Cyclosiloxanes	70900-21-9	0.000047	g	3061	0.3061		89	0.0089
Gel Die Encapsulant		Solvents, additives, and other materials	Dimethyl Siloxane	69430-24-6	0.000712	g	45918	4.5918		1348	0.1348
Copper Lead Frame	0.2731					g					
Copper Lead Frame		Metals	Copper, metal and alloys	7440-50-8	0.123245	g	451286	45.1286		233517	23.3517
Copper Lead Frame		Plastics/polymers	Proprietary Material-Other Epoxy resins	-	0.007128	g	26101	2.6101		13505	1.3505
Copper Lead Frame		Metals	Gold, metal and alloys	7440-57-5	0.000312	g	1141	0.1141		591	0.0591
Copper Lead Frame		Solvents, additives, and other materials	Phosphorus	7723-14-0	0.000104	g	380	0.038		197	0.0197
Copper Lead Frame		Metals	Iron, metal and alloys	7439-89-6	0.002971	g	10877	1.0877		5629	0.5629
Copper Lead Frame		Metals	Nickel, metal and alloys	7440-02-0	0.003568	g	13064	1.3064		6760	0.676
Copper Lead Frame		Metals	Palladium, metal and alloys	7440-05-3	0.000173	g	634	0.0634		327	0.0327
Copper Lead Frame		Plastics/polymers	Polyphenylene Sulfide (PPS)	26125-40-6	0.042771	g	156613	15.6613		81037	8.1037
Copper Lead Frame		Glass	Fibrous-glass-wool	65997-17-3	0.09267	g	339327	33.9327		175579	17.5579
Copper Lead Frame		Metals	Zinc, metal and alloys	7440-66-6	0.000158	g	577	0.0577		299	0.0299
Bonding Agent	0.0118					g					
Bonding Agent		Metals	Proprietary Material-Other aluminum compounds	-	0.00531	g	450000	45		10060	1.006
Bonding Agent		Solvents, additives, and other materials	Other guanidine compounds	-	0.000295	g	25000	2.5		558	0.0558
Bonding Agent		Solvents, additives, and other materials	Carbon Black	1333-86-4	0.000295	g	25000	2.5		558	0.0558
Silicon Semiconductor Die	0.0052	Plastics/polymers	Other phenolic resins	-	0.00059	g	500000	50		11178	1.1178
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-	0.000104	g	20000	2		197	0.0197
Silicon Semiconductor Die		Glass	Silicon, doped	-	0.005096	g	980000	98		9655	0.9655

**LINKS**

MCD LINK

Freescale website <http://www.freescale.com>**GENERAL ENVIRONMENTAL COMPLIANCE LINKS**RoHS signed letter [http://www.freescale.com/files/abstract/corporate/ehs\\_epp/ENV\\_ROHS\\_Freescale\\_Response.pdf](http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ROHS_Freescale_Response.pdf)China RoHS <http://www.freescale.com/chinarohs>REACH signed letter [http://www.freescale.com/files/abstract/corporate/ehs\\_epp/ENV\\_REACH\\_Freescale\\_Response.pdf](http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_REACH_Freescale_Response.pdf)ELV signed letter [http://www.freescale.com/files/abstract/corporate/ehs\\_epp/ENV\\_ELV\\_Freescale\\_Reponse.pdf](http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ELV_Freescale_Reponse.pdf)Conflict Minerals statement [http://www.freescale.com/files/abstract/corporate/ehs\\_epp/ENV\\_CONFLICT\\_METAL\\_Freescale\\_Response.pdf](http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_CONFLICT_METAL_Freescale_Response.pdf)**FREESCALE ENVIRONMENTAL INFORMATION**EPP website <http://www.freescale.com/epp>FAQ [http://www.freescale.com/webapp/sps/site/overview.jsp?code=ENVIRON\\_FAQ](http://www.freescale.com/webapp/sps/site/overview.jsp?code=ENVIRON_FAQ)Technical Service Request [https://www.freescale.com/webapp/servicerequest.create\\_SR.framework?defaultCategory=Hardware Product Support&defaultTopic=Environmentally Preferred Prod](https://www.freescale.com/webapp/servicerequest.create_SR.framework?defaultCategory=Hardware Product Support&defaultTopic=Environmentally Preferred Prod)**LINKS TO BLANK IPC1752 FORMS**Blank IPC1752 v0.9 Form [http://www.freescale.com/files/abstract/corporate/ehs\\_epp/IPC-1752-2\\_v0.9\\_MCD\\_Template.pdf](http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v0.9_MCD_Template.pdf)Blank IPC1752 v1.1 Form [http://www.freescale.com/files/abstract/corporate/ehs\\_epp/IPC-1752-2\\_v1.1\\_MCD\\_Template.pdf](http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf)

IPC1752 XML LINKS

[http://www.freescale.com/mcds/MPXM2010GS\\_IPC1752\\_v09.xml](http://www.freescale.com/mcds/MPXM2010GS_IPC1752_v09.xml)

[http://www.freescale.com/mcds/MPXM2010GS\\_IPC1752\\_v11.xml](http://www.freescale.com/mcds/MPXM2010GS_IPC1752_v11.xml)

[http://www.freescale.com/mcds/MPXM2010GS\\_IPC1752A.xml](http://www.freescale.com/mcds/MPXM2010GS_IPC1752A.xml)